

	Type	Hits	Search Text	DBs	Time Stamp
1	IS&R	621	(228/103).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:29
2	IS&R	187	(228/105).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 11:23
3	IS&R	912	(228/180.5).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 13:07
4	IS&R	175	(228/218).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 13:13
5	IS&R	662	(228/219).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 13:40
6	IS&R	1347	(228/4.5).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:07
7	IS&R	412	(228/8).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:09
8	IS&R	455	(228/9).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:10
9	IS&R	2	((("6824037") or ("6234376")).PN.	USPAT	2005/06/27 14:21

	Type	Hits	Search Text	DBs	Time Stamp
10	BRS	7	("4575602" "4976393" "5110032" "5285949" "5538176" "6068174" "6234376").PN. OR ("6824037").URPN.	US-PGPUB; USPAT; USOCR	2005/06/27 14:21
11	BRS	27	("3627978" "3643321" "4098447" "4323759" "4390771" "4476366" "4564734" "4575602" "4594493" "4732313" "4861533" "4889274" "4909427" "4976393" "5249732" "5393948" "5395037" "5433371" "5538176" "5685476" "5816480" "5958259" "6001724").PN. OR ("6234376").URPN.	US-PGPUB; USPAT; USOCR	2005/06/27 14:24

	Type	Hits	Search Text	DBs	Time Stamp
12	IS&R	3952 2	("228").CLAS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:29
13	IS&R	1210 82	("219").CLAS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:29
14	IS&R	8199 2	("356").CLAS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:30
15	IS&R	1059 38	("359").CLAS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:30
16	IS&R	6049 2	("348").CLAS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:30
17	BRS	3952 21	S12 or S13 or S14 or S15 or S16	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:30
18	BRS	1875 6	S17 and ((semiconductor or chip or integrated or circuit or substrate) near100 (mount\$3 or wire or bond\$3 or solder\$3 or weld\$3)) and (illuminat\$3 or light)	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:35

	Type	Hits	Search Text	DBs	Time Stamp
19	BRS	6753	S17 and ((semiconductor or chip or integrated or circuit or substrate) near100 (mount\$3 or wire or bond\$3 or solder\$3 or weld\$3)) and (illuminat\$3 or light) and (shield\$3 or inert or gas)	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:36
20	BRS	6334	S17 and ((semiconductor or chip or integrated or circuit or substrate) near100 (mount\$3 or wire or bond\$3 or solder\$3 or weld\$3)) and (mount\$3 or bond\$3) and (illuminat\$3 or light) and (shield\$3 or inert or gas)	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:36

	Type	Hits	Search Text	DBs	Time Stamp
21	BRS	1059	\$17 and ((semiconductor or chip or integrated or circuit or substrate) near100 (mount\$3 or wire or bond\$3 or solder\$3 or weld\$3)) and (mount\$3 or bond\$3) and (illuminat\$3 or light) and ((shield\$3 or inert) near10 gas)	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:37
22	BRS	321	\$17 and ((semiconductor or chip or integrated or circuit or substrate) near100 (mount\$3 or wire or bond\$3 or solder\$3 or weld\$3)) and ((mount\$3 or bond\$3) near100 (illuminat\$3 or light)) and ((shield\$3 or inert) near10 gas)	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:38

	Type	Hits	Search Text	DBs	Time Stamp
23	BRS	320	\$17 and ((semiconductor or chip or integrated or circuit or substrate) near50 (mount\$3 or wire or bond\$3 or solder\$3 or weld\$3)) and ((mount\$3 or bond\$3) near50 (illuminat\$3 or light)) and ((shield\$3 or inert) near10 gas)	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:38
24	BRS	9	\$17 and ((semiconductor or chip or integrated or circuit or substrate) near50 (mount\$3 or wire or bond\$3 or solder\$3 or weld\$3)) and (((mount\$3 or bond\$3) near50 (illuminat\$3 or light)) near100 ((shield\$3 or inert) near10 gas))	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:39

	Type	Hits	Search Text	DBs	Time Stamp
25	BRS	303	\$17 and ((semiconductor or chip or circuit or substrate) near50 (mount\$3 or wire or bond\$3 or solder\$3 or weld\$3)) and ((mount\$3 or bond\$3) near50 (illuminat\$3 or light)) and ((shield\$3 or inert) near10 gas)	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:40
26	BRS	294	\$17 and ((semiconductor or chip or circuit or substrate) near50 (mount\$3 or bond\$3 or solder\$3 or weld\$3)) and ((mount\$3 or bond\$3) near50 (illuminat\$3 or light)) and ((shield\$3 or inert) near10 gas)	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:41

	Type	Hits	Search Text	DBs	Time Stamp
27	BRS	269	\$17 and ((semiconductor or chip or circuit or substrate) near50 (mount\$3 or bond\$3 or solder\$3)) and ((mount\$3 or bond\$3) near50 (illuminat\$3 or light)) and ((shield\$3 or inert) near10 gas)	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:41
28	BRS	106	\$17 and (((semiconductor or chip or circuit or substrate) near50 (mount\$3 or bond\$3 or solder\$3)) near200 ((mount\$3 or bond\$3) near50 (illuminat\$3 or light)) and ((shield\$3 or inert) near10 gas))	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:41

	Type	Hits	Search Text	DBs	Time Stamp
29	BRS	106	S17 and (((semiconductor or chip or circuit or substrate) near50 (mount\$3 or bond\$3 or solder\$3)) near100 ((mount\$3 or bond\$3) near50 (illuminat\$3 or light)) and ((shield\$3 or inert) near10 gas))	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:42
30	BRS	104	S17 and (((semiconductor or chip or circuit or substrate) near20 (mount\$3 or bond\$3 or solder\$3)) near100 ((mount\$3 or bond\$3) near50 (illuminat\$3 or light)) and ((shield\$3 or inert) near10 gas))	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:42

	Type	Hits	Search Text	DBs	Time Stamp
31	BRS	104	\$17 and (((semiconductor or chip or circuit or substrate) near20 (mount\$3 or bond\$3 or solder\$3)) near50 ((mount\$3 or bond\$3) near50 (illuminat\$3 or light)) and ((shield\$3 or inert) near10 gas))	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:42
32	BRS	98	\$17 and (((semiconductor or chip or circuit or substrate) near20 (mount\$3 or bond\$3 or solder\$3)) near50 ((mount\$3 or bond\$3) near20 (illuminat\$3 or light)) and ((shield\$3 or inert) near10 gas))	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:42

	Type	Hits	Search Text	DBs	Time Stamp
33	BRS	87	\$17 and (((semiconductor or chip or circuit or substrate) near10 (mount\$3 or bond\$3 or solder\$3)) near50 ((mount\$3 or bond\$3) near20 (illuminat\$3 or light)) and ((shield\$3 or inert) near10 gas))	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:43
34	BRS	940	(((semiconductor or chip or circuit or substrate) near10 (mount\$3 or bond\$3 or solder\$3)) near20 ((mount\$3 or bond\$3) near20 (illuminat\$3 or light)) and ((shield\$3 or inert) near10 gas))	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:43

	Type	Hits	Search Text	DBs	Time Stamp
35	BRS	85	\$17 and (((semiconductor or chip or circuit or substrate) near10 (mount\$3 or bond\$3 or solder\$3)) near20 ((mount\$3 or bond\$3) near20 (illuminat\$3 or light)) and ((shield\$3 or inert) near10 gas))	US-PGPUB; USPAT; EPO; JPO; DERWENT	2005/06/27 14:43